

Spike Safe Floating VI Design & Associated FET Testing Methods



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How to prevent pretty (but destructive) floral patterns on probe cards (that cost more every day)?



Introduction & Problem Statement

Proposed Design & Test Methods



Benefits & On Board Use



What is a floating VI?

- A Source / Measure Instrument (also often called a VI) that can be used with its 'Low Side' at any voltage relative to the tester GND
 - Use is often limited by 'isolation' breakdown of the instrument
 - Allows multiples to be 'stacked'
 - Can also be used with a GND reference

GND Referenced VI



Image from : K. Liu and J. Fan, "Challenging solution design and

Where are these used?



...and anywhere else an instrument referenced to a variable potential is needed

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Existing VIs can be challenging to put to use





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High power events get worse and typically exceed design capability when bad devices get tested

Defect driven damage event (Wafer Image)





Probe Damage Consequences

Single events often cause expensive equipment to be severely damaged

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Alleviating EOS conditions with a Ballasted Mode





Operation Voltmeter ADC – Used closed loop – Same range as driver Ammeter ADC – Use closed loop – Same Range as driver Driver – Force Line only with selectable series R Voltmeter ADC – Used with high gain as precise VM Ammeter ADC – Preset Threshold Trigger – Metering / Digitizing – Same range as driver = Ammeter = Driver = Voltmeter

Implementing the tests.. rDS-On



Implementing the tests.. Current Limit, Overcurrent & Deglitch





Implementing the tests.. BVDSS, SOA (Valve FETs) & the integrated approach



- Most mixed signal ATEs allow for device & instrument commands to be interlaced well with pattern based control
- All tests that use the high power floating VI can now be integrated into one force voltage (no force I needed) sequence, with the DUT/FET state controlled by communication (or gate control) without spikes or crossovers
- Native VI capabilities can also be retained

High power slow response conditions are eliminated, even in failure modes





..and the resistor instantly starts dissipating power in case of a short.





Design constraints

- Accuracy or calibration of the resistor is not needed
 - The design allows all V & I measurements to be independent of the value of the ballast, as long as the range corner conditions are met
 - Ballast value selection is intended to establish operating ranges for the DUT i.e. a 1A LDO Pass FET rDS-On Test would have an R value different from a 10A Valve FET SOA Test
- Power considerations
 - Worst case power in the path is now much lower & deterministic (good for probe card / hardware design margins)
 - Resistor is energized on a low duty cycle and can be sized accordingly.

Resistor Selection



A choice of values is needed for in-instrument design, to suit diverse power & voltage ranges of use.

The design can be implemented on existing ATEs



ATE Implementations

If V/I has a driver mode, implementation is straightforward as shown alongside (Solid Wire Lines)

ATE's not featuring a driver mode will need to use a voltmeter or an extra VI as meter (Dashed lines added)

Either ways, needles are protected due to peak current reduction

and be injected in with other tests..

- Test / Measure V_{TH1}
- Test / Measure R_{ON} (FET rDS-ON)
- Test / Measure V_{TH2}
- Total Test time
 Reduced 90%



Card Failure Comparative Data



60

55

50

45

40

35

30

25

20

15

10

5

0

Comparative Study of high current related card down failures

Constant Aspects: Product / DPW > 1000 Test Coverage Card Tech

5

5

Failure Events: 5 Wafers : 16735 Needles / Card: 3x Test Time : 1x

Summary & Acknowledgements

- A robust test design intended to reduce un-intentional high current events and related probe failures is presented
- Adaptation of the design to protect needles used with existing slower feedback based clamp instruments and the tradeoffs are discussed
- While alternative approaches to forward looking instrument designs are now available from TI, these are not discussed in this presentation.
- Engineers from across TI's Test & Manufacturing communities have supported the data shown in this presentation